

06/29/01

ISSUE CLASSIFICATION	
Class	Subclass

PATENT NUMBER

O.I.P.E.	PATENT DATE
SCANNED <i>1004</i> Q.A. <i>104</i>	

APPLICATION NO. 09/893588	CONT/PRIOR	CLASS 257	SUBCLASS 35.00	ART UNIT 2811	EXAMINER S. P. M. J. S.
------------------------------	------------	--------------	-------------------	------------------	----------------------------

Takashi Kumamoto

Multi-purpose planarizing/back-grind/pre-underfill arrangements for bumped wafers and dies

PTO-2040
12/89

ISSUING CLASSIFICATION															
ORIGINAL															
CLASS		SUBCLASS				CLASS	CROSS REFERENCE(S)								
							SUBCLASS (ONE SUBCLASS PER BLOCK)								
INTERNATIONAL CLASSIFICATION															

☐ Continued on Issue Slip Inside File Jacket

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS			CLAIMS ALLOWED	
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed.	_____ (Assistant Examiner) _____ (Date)			NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S Patent. No. _____ _____ _____	_____ (Primary Examiner) _____ (Date)			ISSUE FEE	
				Amount Due	Date Paid
<input type="checkbox"/> The terminal ____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) _____ (Date)			ISSUE BATCH NUMBER	
WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368. Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.					

Form **PTO-436A**
(Rev. 6/99)

FILED WITH: ☐ DISK (CRF) ☐ FICHE ☐ CD-ROM
(Attached in pocket on right inside flap)

(FACE)